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## PRODUCTS OR MACHINERY

Main impact of Sn/Ag/Cu alloy on components:

The temperature of use for the components will rise from 220 ° C to approximately 260 ° C. Higher temperatures mean greater stress during assembly, therefore components must be both compatible with these temperatures and guarantee long-term reliability

The surface finishes for the lead-free alloy must have different physical features. The final result must present both a solderability and shelf-life equivalent to those of current alloys

The new flame retardant materials have different physical properties. Components must be able to demonstrate they guarantee the same "fire and moisture resistance" performance

The various features of the components must, therefore, be equivalent to or better than those currently in use, despite the fact they are utilised in more stressful operating conditions

## Company Profile of EAS S.r.I.

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